sPHENIX INTT
- Weekly Report

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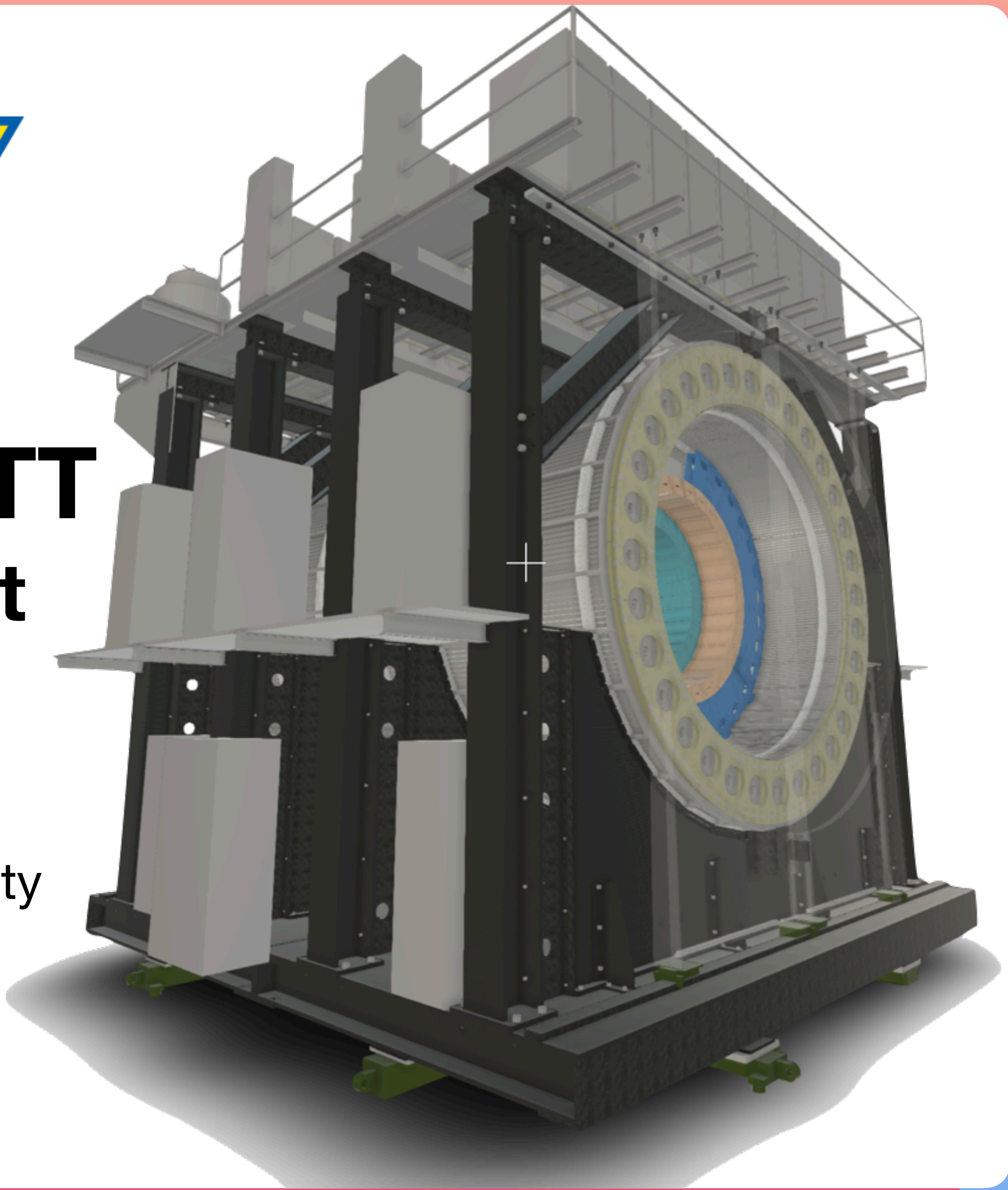
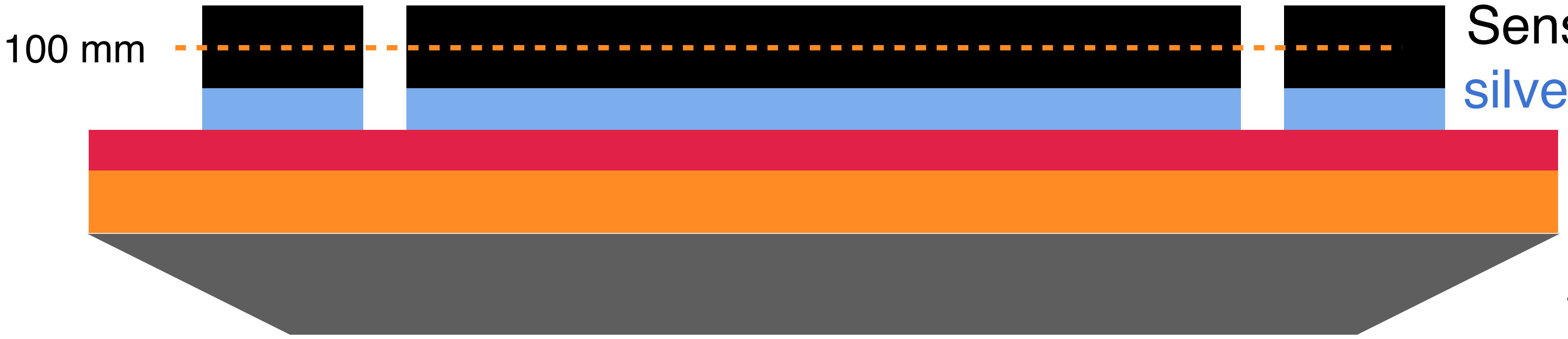
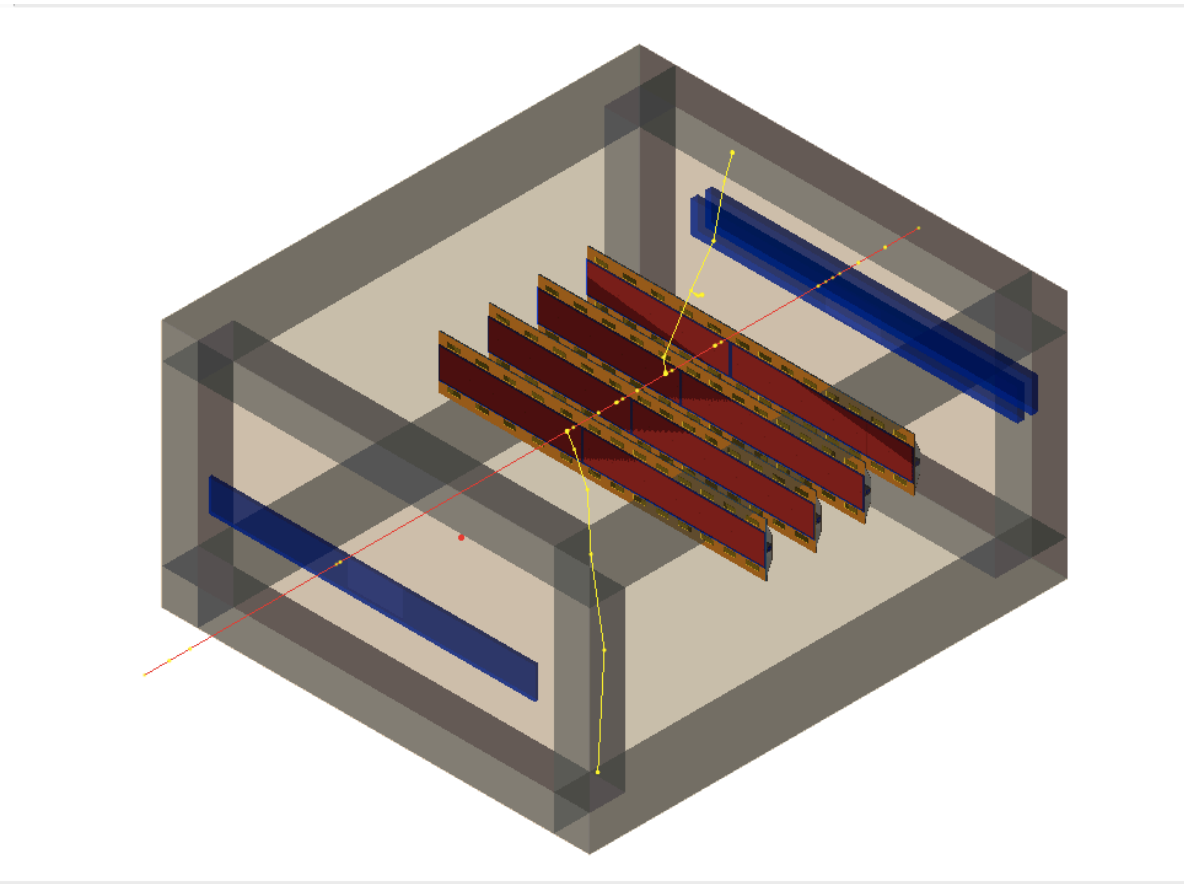
2021/10/15

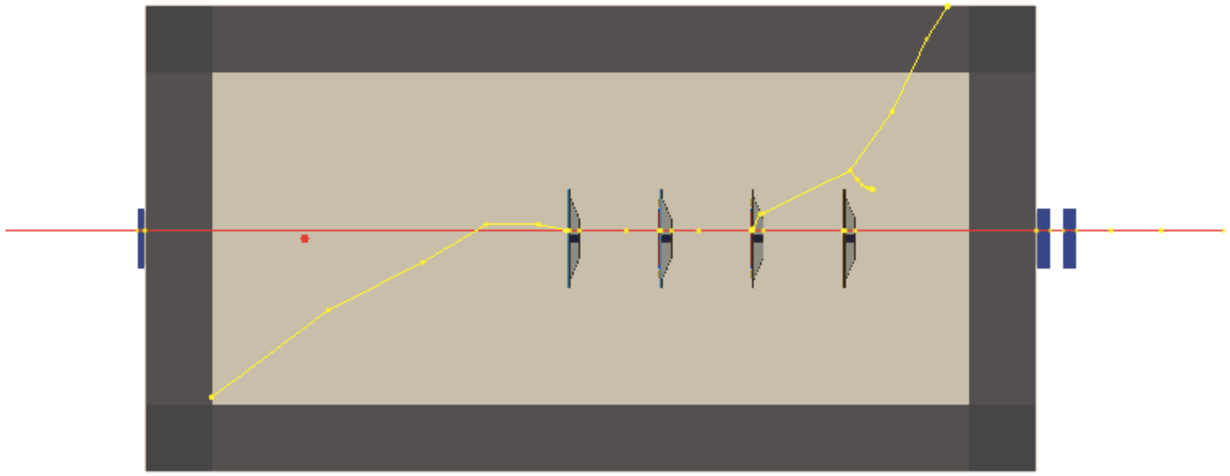


G4 update



Sensor/chip : 320 um
silver epoxy : 50um
HDI copper plate : 37.6um
HDI polyamide : 380 um
stave surface area : Genki





Working with Genki, constructing the model

Half-ladder assembly status

Half-ladder assembly

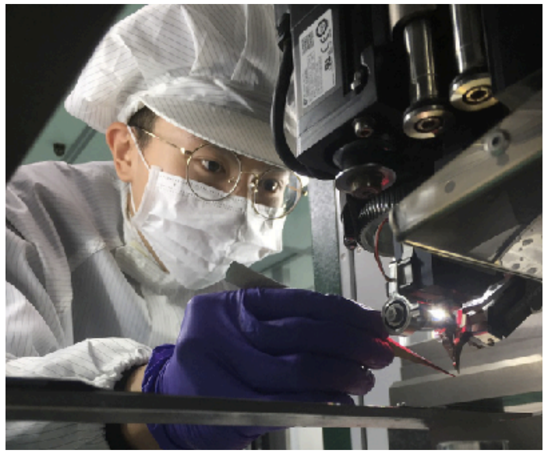
	Total	Good	Not yet bonded & tested	Bad
Chip to HDI	18	1	3	14
Sensor to HDI	2	0	2	0
Encapsulation	1	1	0	0
Thermal cycle	6	5	0	1
On ladder	32	28	X	4

One in NWU

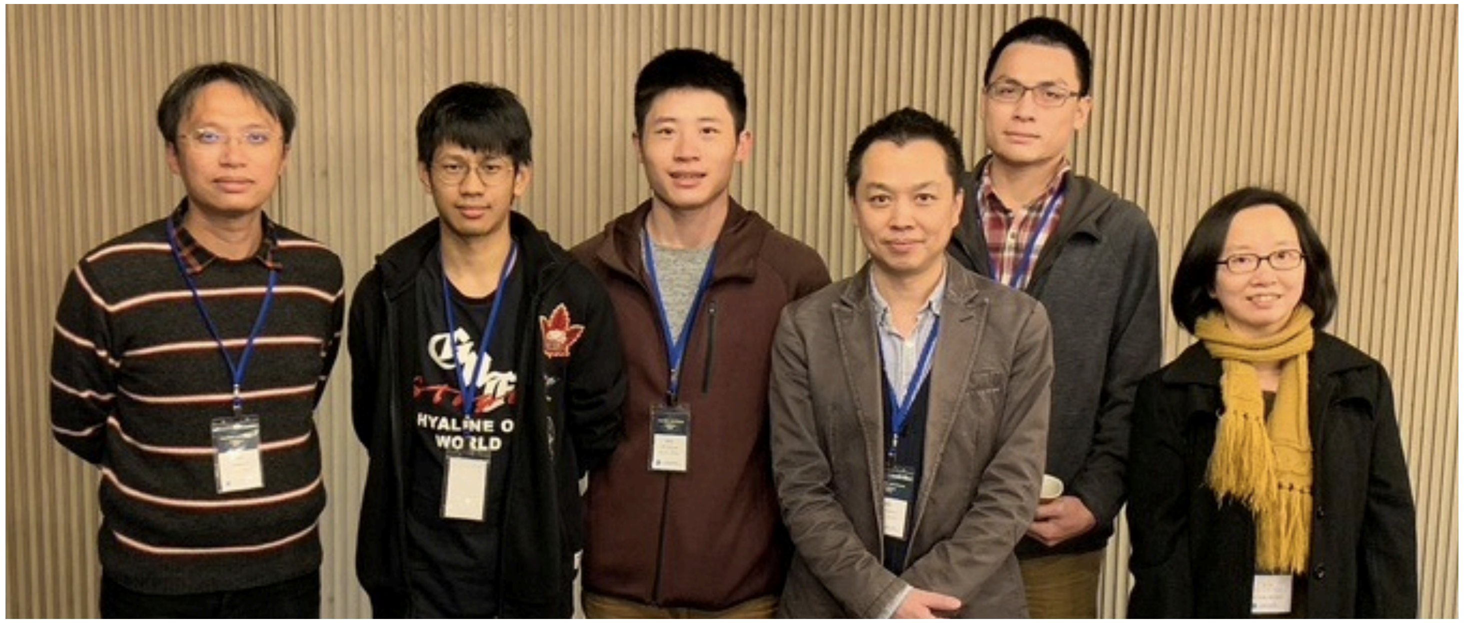
85 sets sensor in Taiwan is confirmed

Back up

Taiwan INTT team


Ou-Wei Cheng


Kai-Yu Cheng


Chia-Ming Kuo Cheng-Wei Shih Lian-Sheng Tsai
Wei-Che Tang Rong-Shyang Lu Jenny Huang

channel ID map